

July 10, 2026

Company name: ES-CON JAPAN Ltd.
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Notice Concerning Issuance of 3rd Unsecured Corporate Bond

ES-CON JAPAN Ltd. hereby announces that it has determined the following terms and conditions for the issuance of its 3rd Series of Unsecured Corporate Bonds. The proceeds from these bonds will be allocated as working capital for the expansion of domestic and overseas development projects. This issuance is being undertaken to secure flexible financing to achieve our "Long-Term Vision 2030" and the "5th Medium-Term Management Plan."

1.	Name of the Bonds	ES-CON JAPAN Ltd. 3rd unsecured bonds with early redemption option (with limited inter-bond pari passu clause)
2.	Total amount of issue	15 billion yen
3.	Denomination per bond	100 million yen
4.	Coupon rate	2.796%per annum
5.	Issue price	100% of the principal amount
6.	Redemption price	100% of the principal amount
7.	Pay-in date	July 16, 2026
8.	Maturity date	July 16, 2031
9.	Use of proceeds	Working capital for expansion of domestic and overseas development projects
10.	Coupon payment dates	January 16 and July 16 of each year
11.	Lead managers	Mizuho Securities Co., Ltd. SMBC Nikko Securities Inc. Daiwa Securities Co., Ltd.
12.	Assistant bond administrator	Mizuho Bank, Ltd.
13.	Book-entry transfer institution	Japan Securities Depository Center, Inc.
14.	Rating	AA-(Japan Credit Rating Agency, Ltd.)